

SPECIFICATION FOR APPROVAL

DESCRIPTION: 5.50"AMOLED Module
CUSTOMER: BR550105-A1 V.1
Product No:
Released Date: 2023.08.26
Revision: v1

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APPROVED SIGNATURES		

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Record of Revision

Rev	Issue Date	Description	Editor
A0	2023-08-26	Draft	Simon

1 General Specifications

Feature		Spec	Remark
Display Spec	Screen Size (inch)	5,50	
	Display Mode	AMOLED	
	Resolution(dot)	1080(W)× 1920(H)	
	Active Area(mm)	68.26(W)× 121.34 (H)	
	Pixel Pitch (um)	-(W)× -(H)	
	Technology Type	LTPS	
	Color Depth	16.7M	
	Interface	MIPI 4LANE	
	Surface Treatment	Hard Coating	
Mechanical Characteristics	TP Outline	TBD	
	Module Outline Dimension(W x H xD)(mm)	70.36(W)x127.34(H)x2.17(D)	
	Weight (g)	TBD	
Electronic	Driver IC(Type)	CH13721	
	Touch IC(Type)	CST148	

Note 1: Requirements on Environmental Protection: RoHS.

2 Input/output Terminals

2.1 Main FPC Pin Assignment

FPC connector: FH26-39S-0.3SHW.

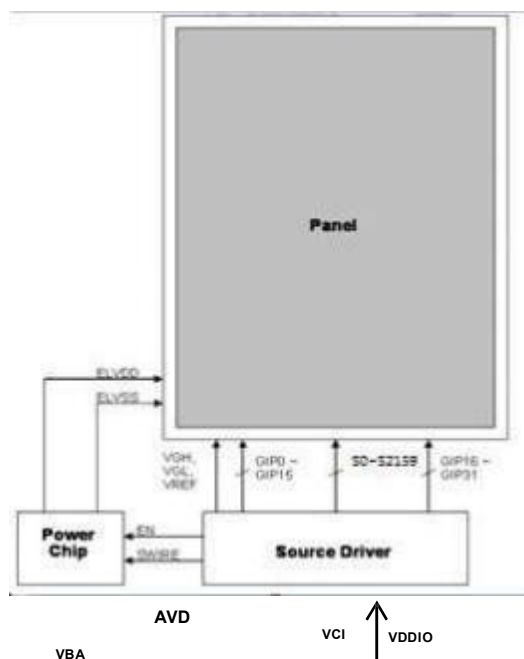
No	Symbol	I/O	Description
1	GND	GND	GND
2	GND	GND	GND
3	GND	GND	GND
4	VBAT	P	Power supply for PM IC
5	VBAT	P	Power supply for PM IC
6	VBAT	P	Power supply for PM IC
7	VBAT	P	Power supply for PM IC
8	VBAT	P	Power supply for PM IC
9	GND	GND	GND
10	OTPV	P	Power supply for MTP Programming or Erase.
11	TE	O	Tearing effect pin
12	GND	GND	GND
13	D3P	I/O	MIPI-DSI data differential signal pins.
14	D3N	I/O	MIPI-DSI data differential signal pins.

15	GND	GND	GND
16	D0P	I/O	MIPI-DSI data differential signal pins.
17	D0N	I/O	MIPI-DSI data differential signal pins.
18	GND	GND	GND
19	DKP	I/O	MIPI-DSI data differential signal pins.
20	DKN	I/O	MIPI-DSI data differential signal pins.
21	GND	GND	GND
22	D1P	I/O	MIPI-DSI data differential signal pins.
23	D1N	I/O	MIPI-DSI data differential signal pins.
24	GND	GND	GND
25	D2P	I/O	MIPI-DSI data differential signal pins.
26	D2N	I/O	MIPI-DSI data differential signal pins.
27	GND	GND	GND
28	RESX	I	The external reset input for LCD
29	VDDIO	P	Power Supply for display logic circuit
30	VCI	P	Power Supply for analog Circuit
31	NC	-	NC

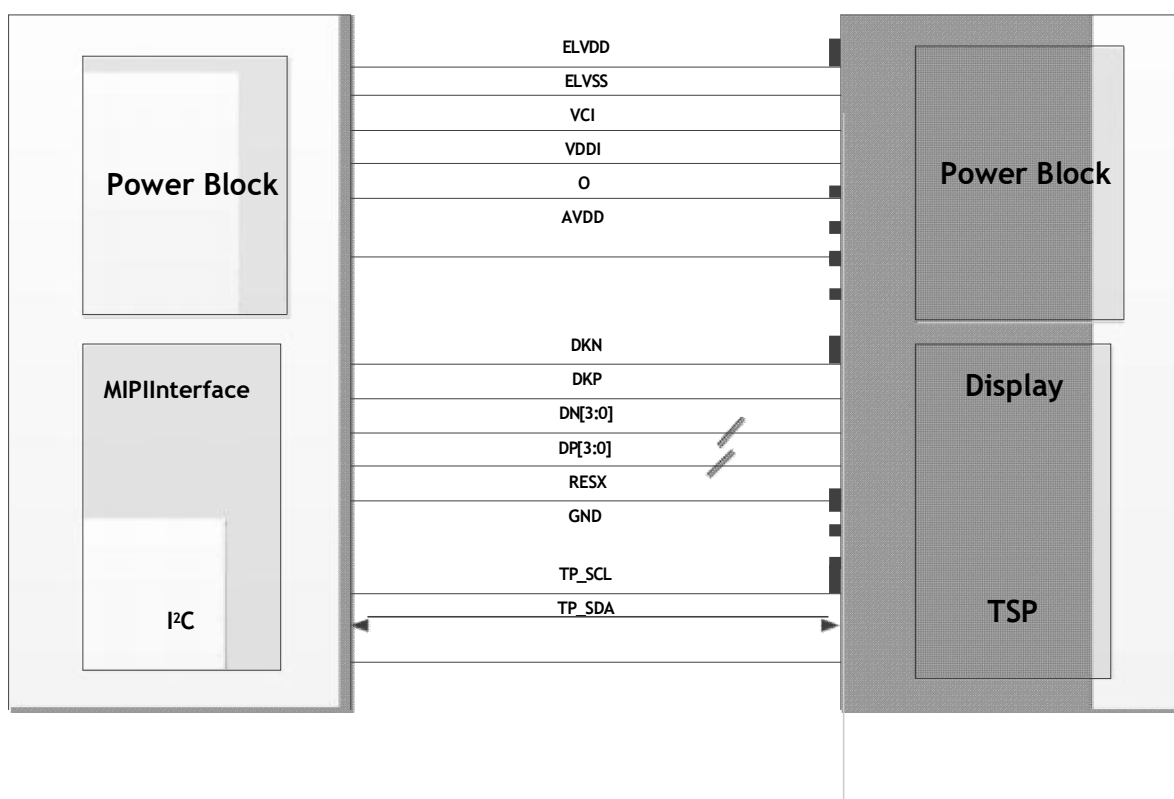
32	GND	GND	GND
33	TP_AVDD_ 3P3V	P	Analog Power for TP
34	TP_IOVCC	P	IO Voltage supply for TP
35	TP_SDA	I/O	SDA pin for TP
36	TP_SCL	I/O	SCL pin for TP
37	TP_RST	I	Reset Pin for TP
38	TP_INT	I/O	INT Pin for TP
39	GND	GND	GND

Note: I=Input; O=Output; P=Power; I/O=Input /Output

2.2 Circuit block diagram (Display)



2.3 MCU and Display Module Interface Configuration



3 Absolute Maximum Ratings

3.1 Driving AMOLED Panel

Maximum Ratings (Voltage Referenced to VSS) Vss = 0V, Ta=25°C

Item	Symbol	MIN	MAX	Unit
Analog Power supply	VCI	-0.3	+5.5	V
Logic Power supply	VDDIO	-0.3	+5.5	V
Positive Power Input	ELVDD	-	-	V
Negative Power Input	ELVSS	-	-	V
Analog Power supply	AVDD	-	-	V

Note: Functional operation should satisfy the limit sin the Electrical Characteristic stables or Pin

Description section. If the module exceeds the absolute maximum ratings, permanent damage may occur. Besides, if the module is operated with the absolute maximum ratings for along time, there liability may also drop.

4 Electrical Characteristics

4.1 Driving AMOLED Panel

Item		Symbol	MIN	TYP	MAX	Unit
Logic Power supply		VDDIO	1.65	1.80	3.3	V
Analog Power supply		VCI	2.65	3	3.6	V
ELVDD Supply Voltage		ELVDD	-	4.6	-	V
ELVSS Supply Voltage		ELVSS	-5	-	-1	V
Interface operating voltage		AVDD	4.5	6.4	6.5	
Input Signal Voltage	High Level	VIH	0.70*VDDIO	-	VDDIO	V
	Low Level	VIL	VSS	-	0.3*VDDIO	V
Output Signal Voltage	High Level	VOH	0.80*VDDIO	-	VDDIO	V
	Low Level	VOL	0.00	-	0.20*VDDIO	V
Normal		I _{ELVDD}	-	200	-	mA
		I _{ELVSS}	-	200	-	mA
		I _{VCI}	-	2.1	-	mA
		I _{VDDIO}	-	50	-	mA
		I _{avdd}	-	TBD	-	mA
Stand-by		I _{VCI}	-	38	-	uA
		I _{VDDIO}	-	168	-	uA

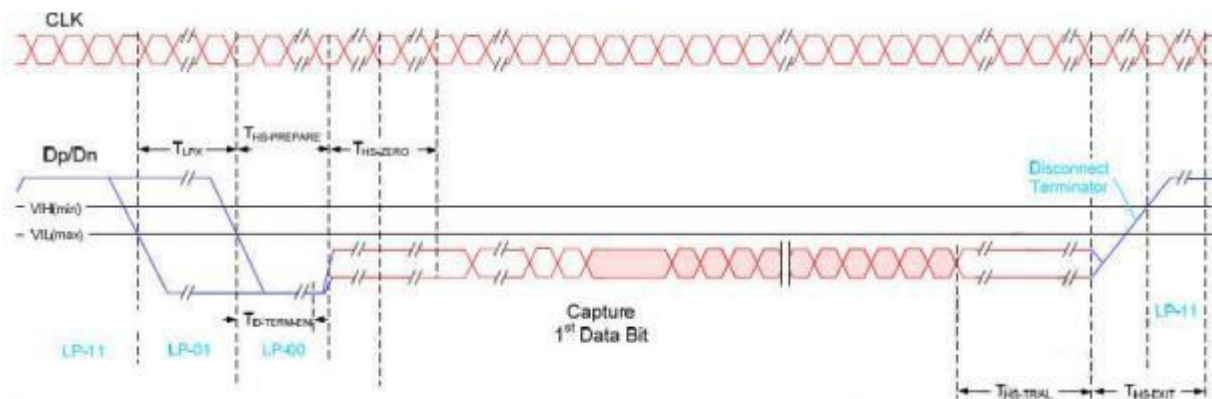
Ta=25°C

Note1: The input digital voltage is the I/O reference voltage.

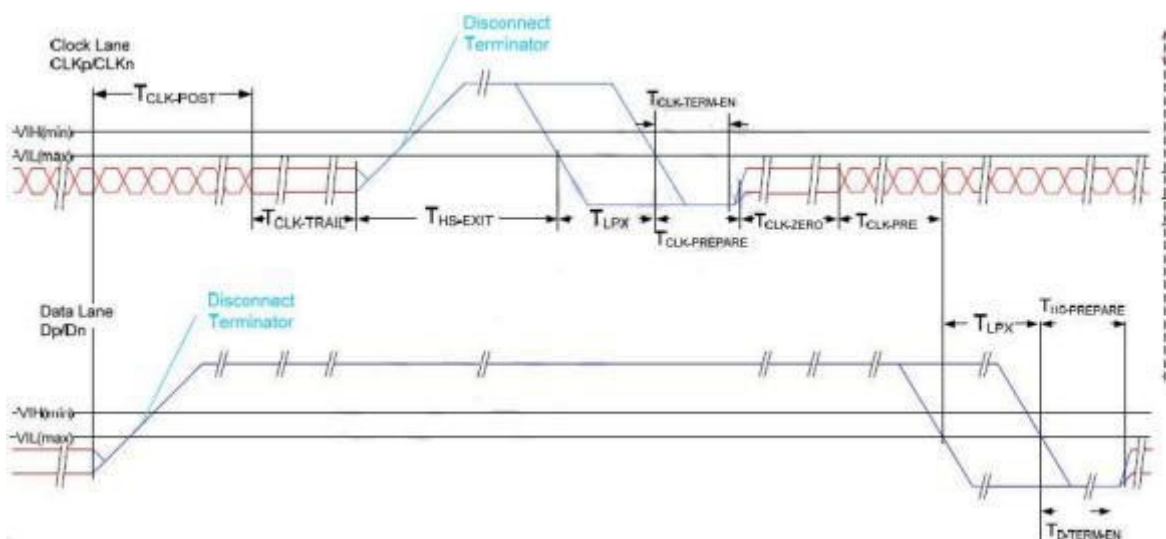
5AC Characteristics

5.1 MIPI Interface Characteristics

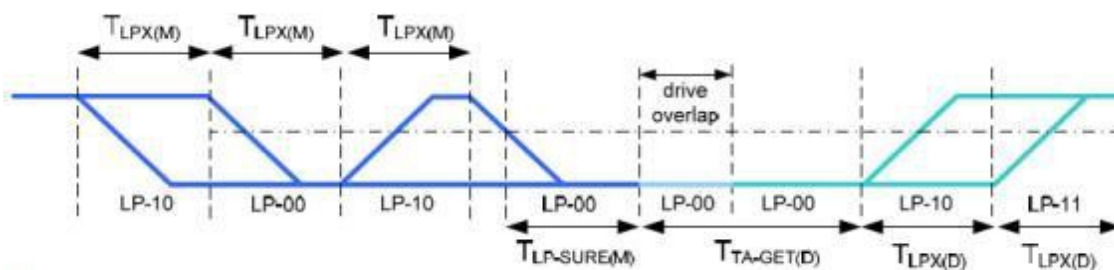
HS Data Transmission Burst



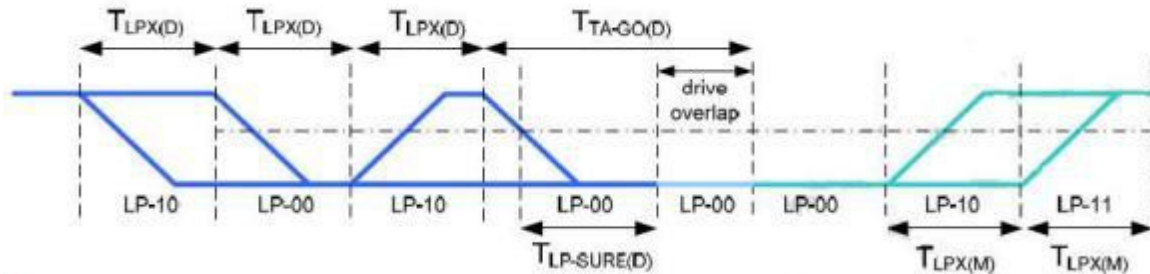
HS clock transmission



Turnaround Procedure



Bus turnaround (BAT) from MPU to display module timing



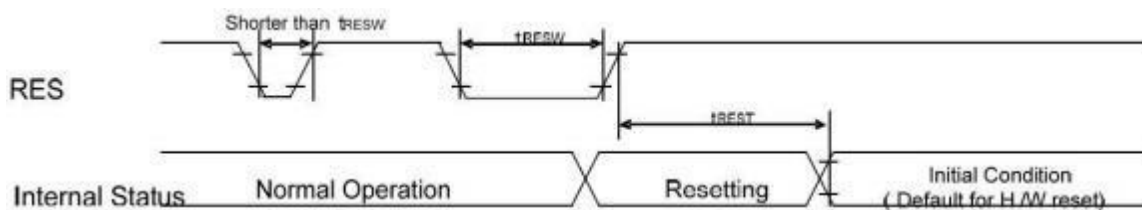
Timing Parameters:

Parameter	Description	Min	Typ	Max	Unit
$T_{CLK-POST}$	Time that the transmitter continues to send HS clock after the last associated Data Lane has transitioned to LP Mode. Interval is defined as the period from the end of $T_{HS-TRAIL}$ to the beginning of $T_{CLK-TRAIL}$.	$60ns + 52 \cdot UI$			ns
$T_{CLK-TRAIL}$	Time that the transmitter drives the HS-0 state after the last payload clock bit of a HS transmission burst.	60			ns
$T_{HS-EXIT}$	Time that the transmitter drives LP-11 following a HS burst.	300			ns
$T_{CLK-TERM-EN}$	Time for the Clock Lane receiver to enable the HS line termination, starting from the time point when D_n crosses $V_{IL,MAX}$.	Time for D_n to reach $V_{TERM-EN}$		38	ns
$T_{CLK-PREPARE}$	Time that the transmitter drives the Clock Lane LP-00 Line state immediately before the HS-0 Line state starting the HS transmission.	38		95	ns
$T_{CLK-PRE}$	Time that the HS clock shall be driven by the transmitter prior to any associated Data Lane beginning the transition from LP to HS mode.	8			UI
$T_{CLK-PREPARE} + T_{CLK-ZERO}$	$T_{CLK-PREPARE}$ + time that the transmitter drives the HS-0 state prior to starting the Clock.	300			ns
$T_{D-TERM-EN}$	Time for the Data Lane receiver to enable the HS line termination, starting from the time point when D_n crosses $V_{IL,MAX}$.	Time for D_n to reach $V_{TERM-EN}$		$35 ns + 4 \cdot UI$	
$T_{HS-PREPARE}$	Time that the transmitter drives the Data Lane LP-00 Line state immediately before the HS-0 Line state starting the HS transmission	$40ns + 4 \cdot UI$		$85 ns + 6 \cdot UI$	ns
$T_{HS-PREPARE} + T_{HS-ZERO}$	$T_{HS-PREPARE}$ + time that the transmitter drives the HS-0 state prior to transmitting the Sync sequence.	$145ns + 10 \cdot UI$			ns
$T_{HS-TRAIL}$	Time that the transmitter drives the flipped differential state after last payload data bit of a HS transmission burst	$60ns + 4 \cdot UI$			ns

Parameter	Description	Min	Typ	Max	Unit	Notes
$T_{LPX(M)}$	Transmitted length of any Low-Power state period of MCU to display module	50		150	ns	1,2
$T_{TA-SURE(M)}$	Time that the display module waits after the LP-10 state before transmitting the Bridge state (LP-00) during a Link Turnaround.	$T_{LPX(M)}$		$2 \cdot T_{LPX(M)}$	ns	2
$T_{LPX(D)}$	Transmitted length of any Low-Power state period of display module to MCU	50		150	ns	1,2
$T_{TA-GET(D)}$	Time that the display module drives the Bridge state (LP-00) after accepting control during a Link Turnaround.		$5 \cdot T_{LPX(D)}$		ns	2
$T_{TA-GO(D)}$	Time that the display module drives the Bridge state (LP-00) before releasing control during a Link Turnaround.		$4 \cdot T_{LPX(D)}$		ns	2
$T_{TA-SURE(D)}$	Time that the MPU waits after the LP-10 state before transmitting the Bridge state (LP-00) during a Link Turnaround.	$T_{LPX(D)}$		$2 \cdot T_{LPX(D)}$	ns	2

5.2 Display RESET Timing Characteristics

Reset n put timing:



VDDIO=1.65 to 3.3V, VDD=2.7 to 3.6V, AGND=DGND=0V, Ta=-40 to 85°C

Timing Parameters

Symbol	Parameter	Related Pins	MIN	TYP	MAX	Note	Unit
t_{RESW}	*1) Reset low pulse width	RESX	10	-	-	-	μs
t_{REST}	*2) Reset complete time	-	-	-	5	When reset applied during Sleep in mode	ms
		-	-	-	120	When reset applied during Sleep out mode	ms

Note1. Spike caused by an electrostatic discharge on RESX line does not cause irregular system reset according to the table below.

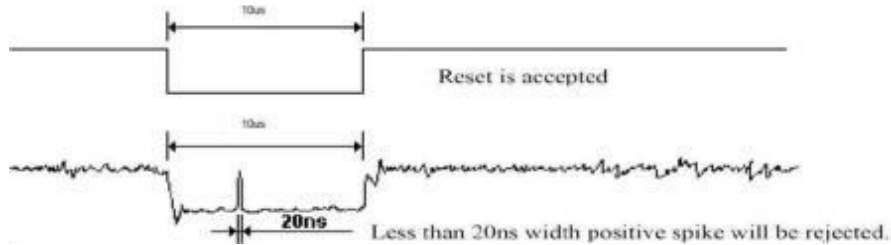
RESX Pulse	Action
Shorter than 5 μs	Reset Rejected
Longer than 10 μs	Reset
Between 5 μs and 10 μs	Reset starts (It depends on voltage and temperature condition.)

Note2. During the resetting period, the display will be blank (The display is entering blanking sequence).

Whose maximum time is 120 ms, when Reset Starts in Sleep Out-mode. The display remains blank in Sleep In-mode) and then return to Default condition for H/W reset.

Note3. During Reset Complete Time, data in OTP will be latched to internal register during this period. This loading is do nee very time when there is H/W reset complete time(t_{REST})with in 5ms after a rising edge of RESX.

Note4 . Spike Rejection also applies during a valid reset pulse as shown below:



Note5. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120 msec.

5 . 3 TE Timing Characteristics

Mode1 , The Tearing Effect Output line consists of V- Blanking information only.



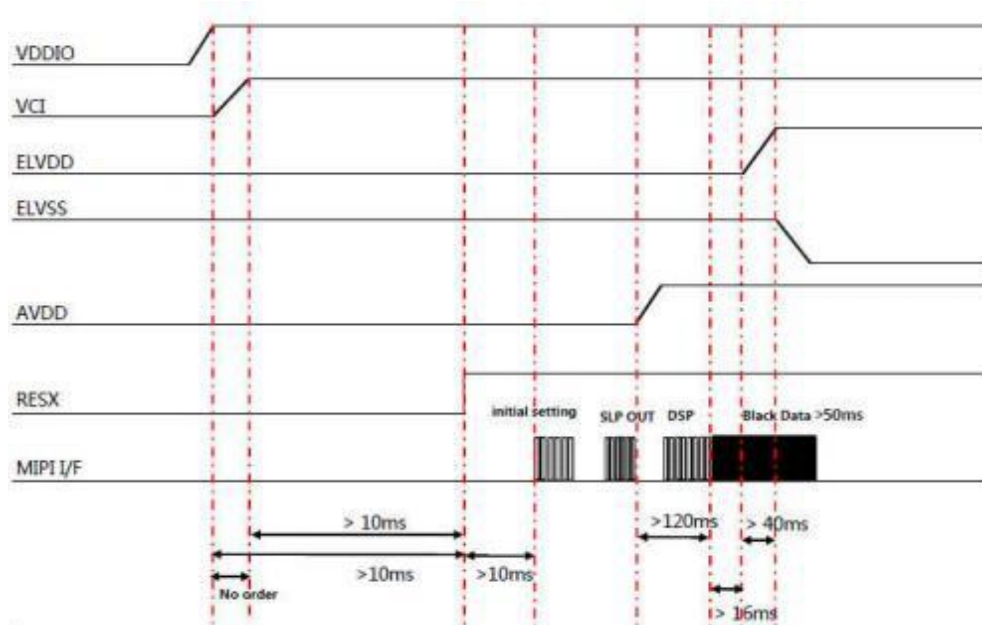
Tvdh = The display is not updated from the frame memory.

TvdI= The display is updated from the frame memory.

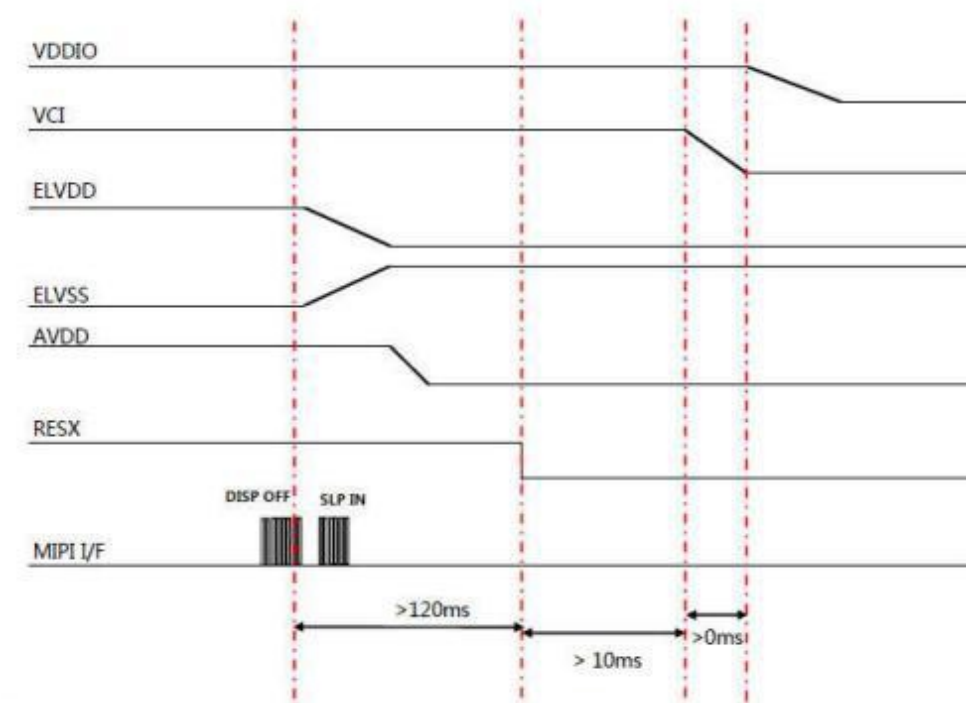
6 Recommended Operating Sequence

6.1 Display Power on / off Sequence

6.1.1 Power On Sequence



6.1.2 Power Off Sequence



6.2 2 Brightness control

Use“ command 5 1 0 0 h, data xxh” to adjust the Manual Brightness value of the display:

In principle relationship is that 0 0 h value means the lowest brightness and FFh value means the highest brightness.

Inst/Para	R/W	Address		Date Type	Description
		MIPI	Other		
BRTCTRL	W	51h	5100h	Hex	Value form 0~255(FF)

7OpticalCharacteristicsOpticalSpecification

Item		Symbol	Condition	Min	Typ	Max	Unit	Remark
View Angle		θT	CR≥10	-	-	80	Degree	Note2 Test Equipment: CS2000A
		θB		-	-	80		
		θL		-	-	80		
		θR		-	-	80		
Contrast Ratio		CR	θ=0°	100000				Note1 Note3 Test Equipment: CS2000A
Response Time		T _{ON}	25℃			1	ms	Note1 Note4 Test Equipment: AdmesyMSE
		T _{OFF}						
Chromaticity	White	x		(0.280)	(0.300)	(0.320)		Test Equipment: CS2000A Note: Chromaticity can be modified according to customer demand
		y		(0.290)	(0.310)	(0.330)		
	Red	x		(0.650)	(0.680)	(0.710)		
		y		(0.285)	(0.315)	(0.345)		
	Green	x		(0.210)	(0.250)	(0.290)		
		y		(0.670)	(0.710)	(0.750)		
	Blue	x		(0.110)	(0.140)	(0.170)		
		y		(0.017)	(0.047)	(0.077)		
Uniformity		U		80	85		%	Note1 Note6 Test Equipment: CS2000A
NTSC				97	105		%	Note5
Luminance		L	Normal	305	450	495	Cd/m ²	Note1 Note7 Test Equipment: CS2000A
Cross-talk						2	%	Note8 Test Equipment: CS2000A

Gamma			2.0	2.2	2.4		Gamma=2.2±0.2 TestEquipment: CS2000A
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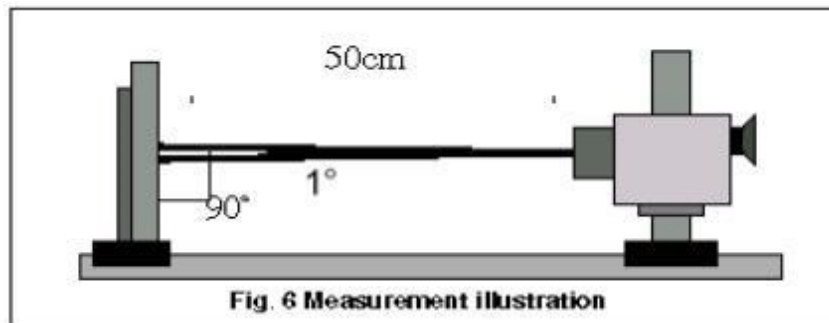
Test Conditions:

The ambient temperature is 25°C.

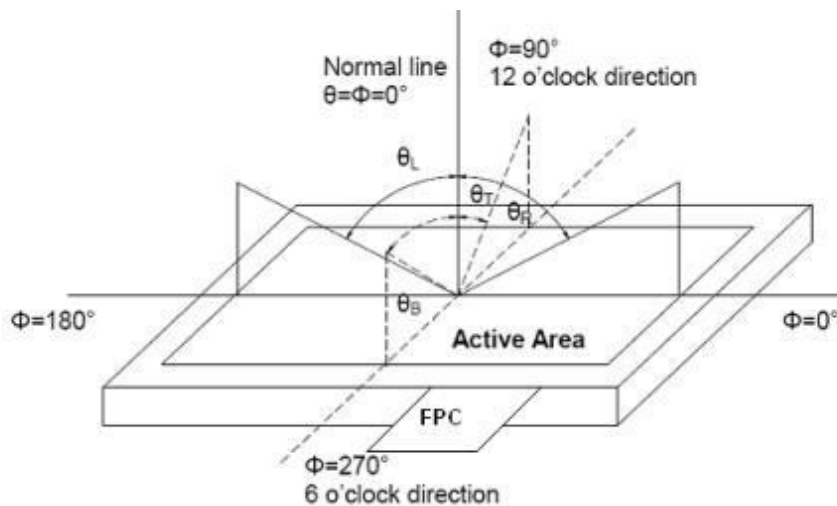
1. The test systems refer to Note 1 and Note 2.

Note1: Definition of optical measurement system.

The optical characteristics should be measured in darkroom. The optical properties are measured at the center point of the AMOLED screen. All input terminals AMOLED panel must be ground when measuring the center area of the panel.



Note 2: Definition of viewing angle range and measurement system.



Note 3: Definition of contrast ratio

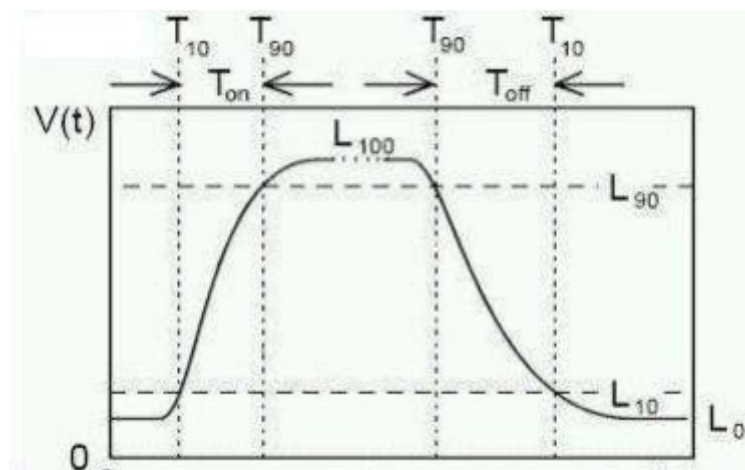
$$\text{Contrast ratio (CR)} = \frac{\text{Luminance measured when LCD is on the "white" state}}{\text{Luminance measured when LCD is on the "Black" state}}$$

"White state ":A state where the AMOLED should be driven by V white.

"Black state": A state where the AMOLED should be driven by V black.

Note 4: Definition of response time

The response time is defined as the AMOLED optical switching time interval between "White" state and "Black" state. Rise time (T_{ON}) is the time between photodetector output intensity changing from 10% to 90%. And fall time (T_{OFF}) is the time between photo detect or out put intensity changing from 90% to 10%.



Note 5: Definition of color chromaticity (CIE1931)

Color coordinates are measured at the center point of AMOLED.

Note 6: Definition of luminance uniformity

Active area is divided into 9 measuring areas (Refer Fig. 2). Every measuring point is placed at the center of each measuring area.

$$\text{Luminance Uniformity}(U) = L_{\min} / L_{\max}$$

L-----Active area length W----- Active area width

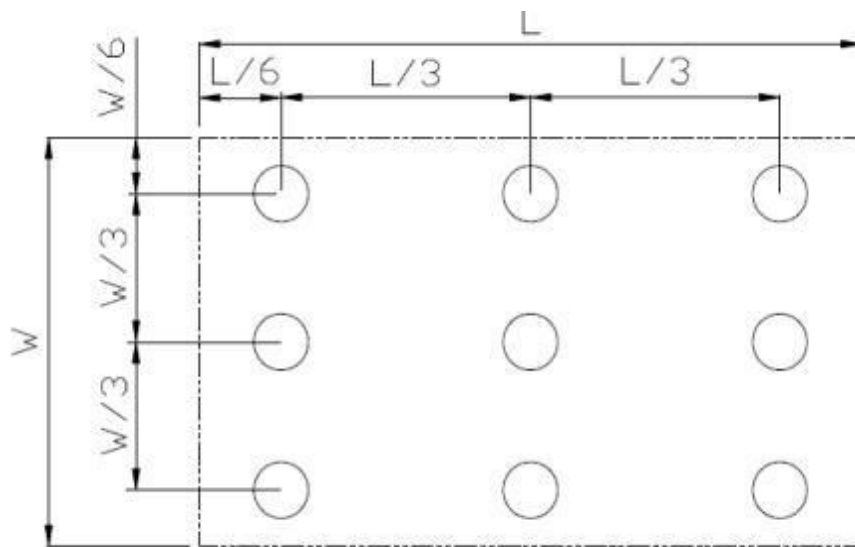


Fig. 2 Definition of uniformity

$L_{\max}$: The measured maximum luminance of all measurement position.

$L_{\min}$: The measured minimum luminance of all measurement position.

Note 7: Definition of luminance:

Measure the luminance of white state at the center point.

Note 8: Cross Talk

A. Measure luminance at the position, P0.

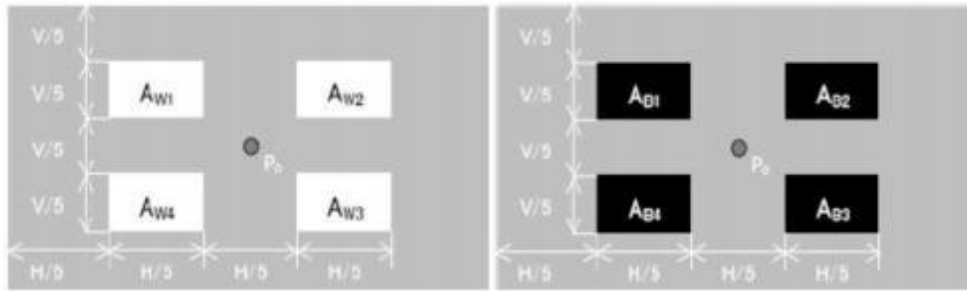
B. Calculate cross talk as below equation.

$$L_{W_OFF} = \frac{L_{W1} + L_{W2} + L_{W3} + L_{W4}}{4}$$

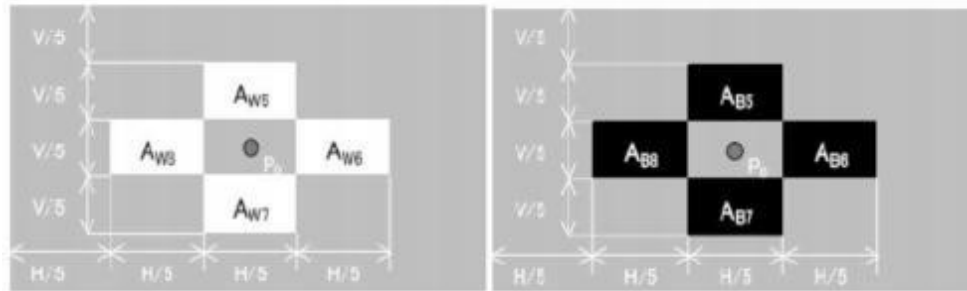
$$L_{B_OFF} = \frac{L_{B1} + L_{B2} + L_{B3} + L_{B4}}{4}$$

$$\text{crosstalk} = \frac{|L_{Wi_ON} - L_{W_OFF}|}{L_{W_OFF}} \times 100\% \quad (i=5 \text{ to } 8)$$

$$\text{crosstalk} = \frac{|L_{Bi_ON} - L_{B_OFF}|}{L_{B_OFF}} \times 100\% \quad (i=5 \text{ to } 8)$$

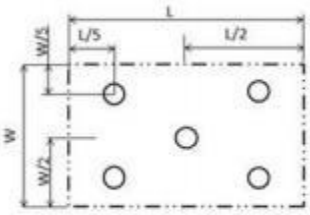


(a) L_{W_OFF} , L_{B_OFF} measuring pattern



(b) L_{W_ON} , L_{B_ON} measuring pattern

8Environmental/Reliability Test

No	Test Item	Condition	Remark
1	High Temperature Operation	+70C, 120hrs	According to the customer request
2	Low Temperature Operation	-20C, 120hrs	According to the customer request
3	High Temperature Storage	+80C, 120hrs	According to the customer request
4	Low Temperature Storage	-30C, 120hrs	According to the customer request
5	High Temperature &High Humidity Operation	60C, 90% RH,120hrs	According to the customer request
6	High Temperature &High Humidity Storage	60C, 90% RH,120hrs	According to the customer request
7	Thermal Shock (Non-operation)	-30C(30 min)~+70C(30 min),Change time:10min, 30Cycles	According to the customer request
8	Electrostatic Discharge (Operation)	C=150pF, R=330Ω , 5points/panel Air:±8KV, 5times; Contact: ± 4 KV, 5 times; (Environment: 1 5 C~ 3 5 C, 30%~60% , 86 Kpa~106 Kpa) . 	IEC61000-4-2 GB/T17626.2

9QualityLevel

9.1 AMOLED Module of Characteristic Inspection

The environmental condition and visual inspection shall be conducted as below:

- (1) Ambient temperature: $23 \pm 3^{\circ}\text{C}$
- (2) Humidity: $55 \pm 10\%\text{RH}$
- (3) Ambient light intensity of visual inspection: 800 ~ 1200 lux
- (4) Ambient light intensity of function inspection: ≤ 200 lux
- (5) Viewing Distance: $30 \pm 5\text{cm}$
- (6) Viewing angle (tolerance): the front side $45^{\circ} (Z) \pm 15^{\circ}$
- (7) Inspection time: 10 ± 5 sec

9.2 2 Sampling Procedures for each item acceptance table

Defect type	Sampling Procedures	AQL
Major defect	GB/T2828.1-2003 Inspection level II Normal inspection Single sample inspection	0.65
Minor defect	GB/T2828.1-2003 Inspection level II Normal inspection Single sample inspection	1.0

Major defect:

Any defect may result in functional failure, or reduce the usability of product for its purpose.
For example, electrical failure, deformation and etc.

Minor defect

A defect does not reduce the usability of product for its intended purpose and ununiformity, such as dot defect and etc.

The criteria on major and/or minor judgment will be according with the classification of defects.

9.3 Inspection Item

No	Item	Area	Criterion of Defect			Defect type
1	Dot Defect	AA	Type	DS	Acceptable number	Minor
			Bright Dot	≥ 10 mm	0	
			Dark Dot	≥ 10 mm	4	
			Dark Dot ($\geq$ two)	$\geq 10\text{mm}$	2	

			connections)				
2	No Display	AA	/			Not allowed	Fatal
3	Abnormal Display	AA	/			Not allowed	Fatal
4	Normally white	AA	/			Not allowed	Fatal
5	Line Defect	AA	single line	Bright line	Not allowed	Fatal	
				Dark line	Not allowed		
			Multiple lines	Bright line	Not allowed		
				Dark line	Not allowed		
			Half-Line	Bright line	Not allowed		
				Dark line	Not allowed		
6	Image sticking	AA	Switch to the next screen and display the image of the previous picture			Major	
7	Color&Edge Mura	AA	See limit sample(under full white screen)			Major	
8	Color crast	AA	See limit sample(under full white screen)			Major	
9	Water Ripple	AA	Not allowed			Major	
10	Other mura(Low gray- scale white spot、S- Line Mura)	AA	Not allowed(under full white screen) or See limit sample(under low gray- scale white screen)			Major	
11	TP	AA	TP function NG			Not allowed	Fatal
12	Glass crack	AA、 OA	/			Not allowed	Fatal
13	Screen bump	AA、 OA	Encap surface is not allowed and LTPS does not affect assembly			Major	
14	Lines effects (light visible)	AA	W (mm)	L (mm)	DS (mm)	Acceptabl e number	Minor
			W≤0.03	-	-	Ignore	
			0.03<W≤0.05	L≤5.0	≥10	2	
			0.05<W	-	-	0	
			-	L>5.0	-	0	
15	Points effects (light visible)	AA	D (mm)	DS (mm)		Acceptabl e number	Minor
			D≤0. 1	/		Ignore	

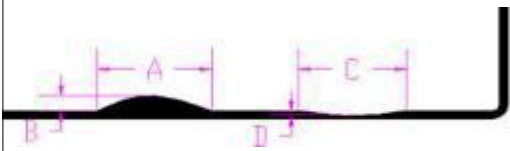
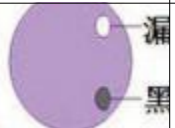
			$0.1 < D \leq 0.25$	≥ 1 0		2	
			$0.25 < D$			0	
16	Glass scratch	AA	W (mm)	L (mm)	DS (mm)	Acceptabl e number	Minor
			$W \leq 0.03$	$L < 5.0$	≥ 10	Ignore	
			$0.03 < W \leq 0.05$	$L \leq 2.0$	≥ 10	Ignore	
				$2.0 < L \leq 5.0$	≥ 10	2	
			$0.05 < W$	-	0	0	
				$L > 5.0$	0	0	
17	Frit Encap sulation	FA	Frit width uniformity. It should not have bubble or breakage.				Major
18	Polarizer crease / indentation	AA	See limit sample				Minor
19	Protective film starved/ overflow glue/ burr	Except AA	No control under $W \leq 0.3\text{mm}$				Minor
20	Polarizer bump point	Whole area	Bump: $D \leq 0.25\text{mm}$, dent $\leq 1\text{mm}$ or See limit sample		Allow 3		Minor
21	Polarizer bubble line	Out of AA, $\leq 0.25\text{ m m}$	Encap surface		Not allowed		Minor
22	Scratches on the Surface of polarizer	Whole area	No harm subject regard less of control				Minor
23	Concave dot、Black and white dot、Polarizer Dent/ Bubble	AA	Front (En cap surface)	D (mm)	DS (mm)	Acceptabl e number	Minor
				$D \leq 0.1$	≥ 10	Ignore	
				$0.1 < D \leq 0.2$	≥ 10	3	
				$0.2 < D$	≥ 10	0	
			Metal material foreign material	/	≥ 10	Not allowed	
24	Polarizer Scratch/ Fiber(Linear)	AA	W (mm)	L (mm)	DS (mm)	Acceptabl e number	Minor
			$W \leq 0.03$	$L \leq 5.0$	≥ 10	Ignore	
			$0.03 < W \leq 0.05$	$L \leq 2.0$	≥ 10	Ignore	
				$2.0 <$	≥ 10	3	

			0.05<W	-	≥10	0	
				L>5.0	≥10	0	
25	Edge/Side breakage	OA	The following Criterion is applicable to any side (unit: mm)				Minor
			Z	X	Y	Acceptable number	
			≤ T	≤2.0	not extended to Circuit Area or Frit	<5	
26	UV glue	Not IC side	Over coating			Not allowed	Minor
		IC side	The coating of IC side is not higher than POL.			Not allowed	
		IC side	The coating of IC side is not higher than POL.			Not allowed	
27	Tuffy glue	IC and FPC bonding area	The coating should not have breakage or Bubble.				Minor
			The coating is not higher than POL.				
		Other area	Tuffy glue is not allowed to interrupt and the diameter of Bubble is not more than 0.5 mm.				
			The coating is not higher than POL.				
		IC	Not allowed				
FPC	Ribbon glue: the width is not more than 1 mm. Dot glue: the diameter is not more than 2 mm.						
28	Rear reinforcement glue of FPC	FPC	The width is not more than 1mm . The height is lower than LTPS.				Minor
29	ACF	Bonding Area	The length of attachment is more than both ends of FPC,which should be range from 0.2 to 1mm. Don't go beyond the edge of panel. Effective lap width of wiring ACF is more than 2/3, which is compared with the width of the gold finger of FPC. Don't have bubble or wrinkle.				Minor
30	FPCA	FPC	The component cannot reverse polarity				Minor
			No wrong insertion				
			FPC should not have serious crease which destroy the line, prick and spots damage. Scratch is not allowed if Cu layer is exposed.				
			The gold fingers should not be oxidized, scraped, folded, impressed, broken, spotted or dissymmetry.				
			Make sure FPC is not scalded, with its location holes not having deficiency or obviously shift.				
			The component of FPC should be the same as BOM				

			list.	
			No remaining soldering Sn	
			No visual particle on the pad line	
31	FPC bonding	Bonding area	Bubble: Visible bubble is not allowed	Minor
			Overhang: The size above 1/2 of soldering electrode of the parts overhang to the LAND is prohibited. The tilt Height less than 0.5mm between FPC and foam.	
	FPC Skew		Not allowed	
32	Package	Other	Products should put into the anti- static trays, with non- overlapping, and the trays should be staggered placed	Minor
			Different products cannot be mixed into the same inner package.	
			The package should not have obvious deformation or breakage . The printing labels type and quantity are correct.	
			The package should have QC signature. ROHS label is Needed if the product is under ROHS control.	

Inspection standard for cover

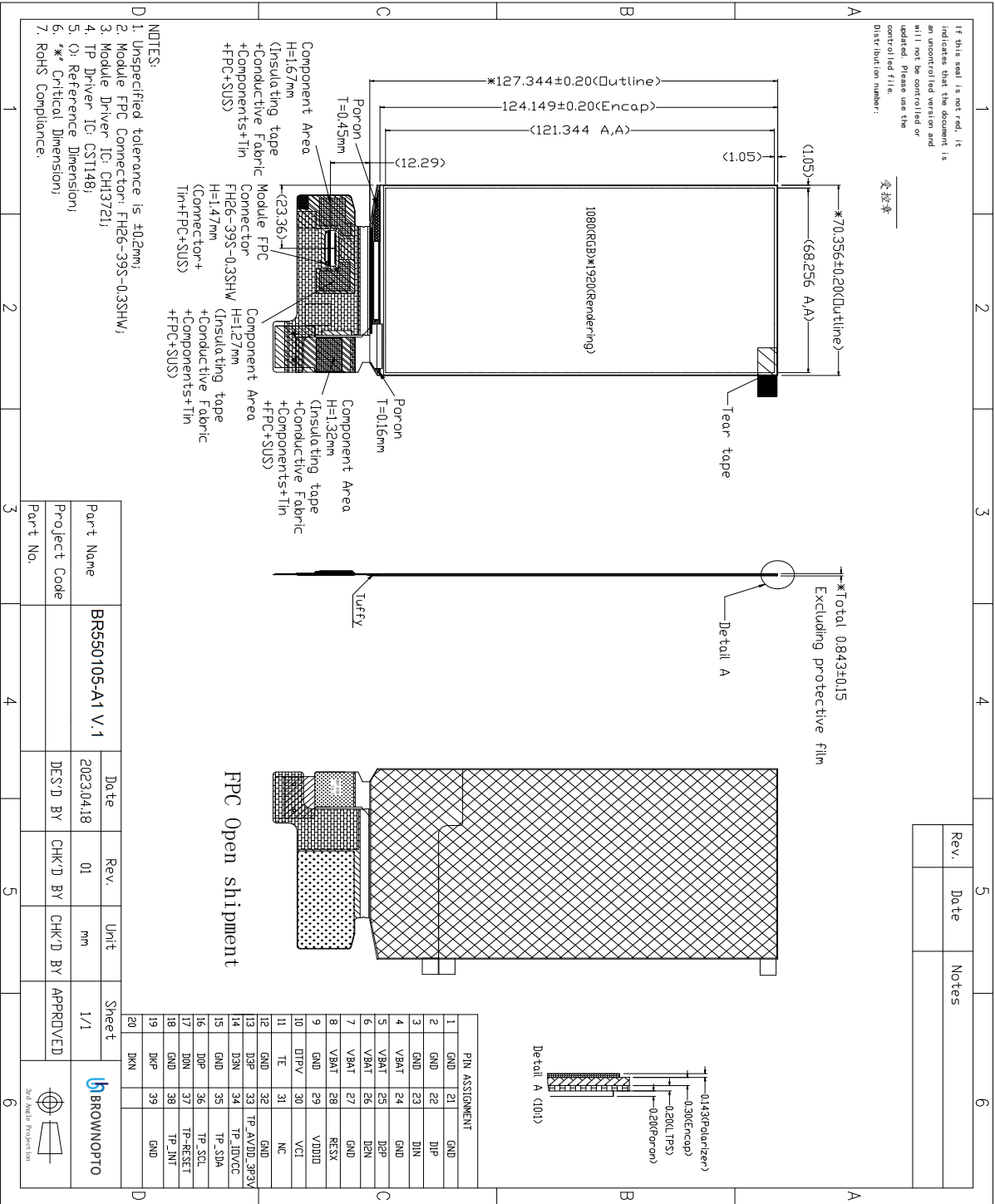
No	Item	Area	Criterion of Defect				Defect type
33	Cover dot、Black and white dot、Polarizer Dent/Bubble	Whole area	D (mm)		DS (mm)	Acceptable number	Minor
			D≤0.15mm		/	Ignore (specks is not allowed)	
			0. 15mm<D<0.25mm		DS≥ 10 mm	2	
			D> 0.25 mm		/	Not allowed	
			Specks: D<0. 15 mm, N>5 in 10 mm*10 mmarea				
34	Cover Scratch/Fiber (Linear)	AA	W(mm)	L(mm)	DS(mm)	Acceptable number	Minor
			W≤0.03 mm	L≤10mm	≥10	Ignore	
			0.03mm<W ≤0.05mm	L≤5.0mm	≥10	2	
			W>0.05	/	/	Not allowed	
			/	L>5.0mm	/	Not allowed	
			Not allowed to scratch				
35	Edge pinhole	Edge of cover	D (mm)	DS (mm)	Acceptable number		Minor
			D< 0.1mm	DS≥ 10mm	One is allowed on each side		

36	Uneven edge of the ink	Edge of cover	W (BorD)	L(AorC)	Acceptable number		Minor	
			$W \leq 0.15\text{mm}$	$L \leq 3\text{mm}$	≤ 2			
37	Ink silk screen serrated	OA area	D (mm)	DS (mm)	Acceptable number		Minor	
			$D \leq 0.2$	$DS \geq 10\text{mm}$	2			
38	Camera Hole	OA area	Breakage or crack: $D \leq 0.1\text{mm}$				Minor	
			Hole is not round: Refer to the limit sample					
			Dot Defect: $D \leq 0.1\text{mm}$, and $N \leq 1$, heterochrosis and line defect are not allowed;					
			Camera hole smudge: not allowed					
39	Printing defect	OA area	Wrongly、Missing、Ghosting and incomplete printing : not allowed				Minor	
			Fonts consistent with the standard characters, no significant difference in visualization					
			Penetrating scratch is not allowed					
40	IR Hole/ Black spots/ Line scratch foreign matter/ Residue	OA area	DS (mm)	Acceptable number			Minor	
			$DS < 0.1$	Ignore				
			$0.1 \leq DS \leq 0.15$	1				
			Note: Not visible on black background, don't affect the transmission rate					
			Foreign body, dirty in IR hole: not allowed					
			Scratched\ Line defects in IR hole: $W \leq 0.03\text{mm}$, $L \leq 1\text{mm}$, $N \leq 1$, Not visible on black background, don't affect the transmission rate.					
			Residual glue in IR hole: not allowed					
41	Cover lens deformation	OA area	Raised height $< 0.15\text{mm}$, and the area is less than 25 % of the entire non- display area in the cover lens				Minor	
		AA area	Deformation is not allowed in AA area					

42	Poor penetration of icons	OA area	DS≤0.15 and N≤1		Minor
43	Cover dirt	Whole area	Not allowed		Minor
44	Cover crack				Fatal
45	Cover paint chips				flaw
46	Burr	Edge of cover	L≤0.05mm, W<0.2mmaccept (The premise does not affect the assembly and function and user operation)		Minor
47	colour difference	OA area	No significant difference in visualization (refer to the Limit sample if necessary)		
48	Overfill	Whole area	Not allowed in AA area		Minor
			The visible part of the periphery cannot be seen after assembly, and cannot affect the assembly		
49	Protective film	Whole area	Film position deviation≤0. 15mm		Minor
			Scratch: no control when don' t damage the body		
			Overfill/ lack of plastic/ Burr: no control		
			Not control the bubble inside the cover protection film		
50	Easy to tear	Cover surface	Function failure\ damaged\ Missing label: not allowed		
			Wrinkle\ Convex- concave point\ dirty\ punching\ burr\ squeeze out: not control		
51	Composite tape	LTPS	Don' t go beyond the edge of panel.		
			Folds\ Light leakage\ Impact assembly or thickness: not allowed		
			Damaged: not allowed		
			Bump does not affect the assembly: not control		
			Punching the bad size meet the drawings requirements: not control		
			Non- wipe dirty\ foreign body: not allowed		
			Foreign objects in accordance with the standard line/ point		
			Burr does not exceed the screen edge: not control		
52	Film warpage	Whole area	Do not have obvious bubbles		
			Gum flower\ Overfill: no control		
52	Film warpage	Whole area	Warpage≤0.2mm		Minor
53	ICON hole	OA area	Chromatic aberration、double image、dot defect、line defect: not allowed (or refer to limited sample)		Minor
54	Earpiece hole	OA area	left- right asymmetry, Hole Rather large/ small or off normal(Out of specification) No chamfer, Uneven polishing: not allowed		
55	Ink bumps	OA area	Positive side reference point defects; The backside does not affect the assembly; Ink over flow or		

			accumulation: not allowed					
56	Cover concave convex point	Whole area	Front:Height&depth ≤ 0. 15 mm, size ≤ 0.4 mm, if necessary reference limit sample					
			Back: Don't affect the fit process is not controlled					
57	Insulation Tape	Bonding area	Obvious wrinkles and bubbles: not allowed				Minor	
		Component area	Scratch/ Gum flower: not control					
			Non- wipe dirty: not allowed					
			Offset cannot exceed the edge of the product, Others are required to the drawings					
			Burr\ Overfill: not control					
			Damaged/ incomplete/ missing paste: not allowed					
58	Cover edge/side breakage	Edge of cover	X	Y	Z	DS	Acceptable number	Minor
			X<0.2mm	Y<0.2mm	Z≤1/2t	DS>5mm	Unilateral ≤2	
			X>0.2mm	/	/	Not allowed		
			/	Y>0.2mm	/	Not allowed		
			/	/	Z>1/2T	Not allowed		
			Cracks are not allowed					
59	Blunt	Whole area	Not allowed				Fatal flaw	
60	Fit bubble	AA	According to the punctate specifications				Minor	
61	Vision area edge defect	OA	D≤0.2mm, DS>10,N≤2 (hole saw tusk less than 2) , if necessary reference limit sample.				Minor	
62	Cover heterochrosis	OA	Heterochrosis side execute according to point defect size,bulk/stick refer to Limited sample				Minor	

10 Mechanical Drawing



11 Precautions for Use of AMOLED Modules

11.1 Handling Precautions:

- 11.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from height.
- 11.1.2 Do not press down the screen on the adjoining areas too hard because the color tone may be shifted.
- 11.1.3 The polarizer covering the display surface of the AMOLED module is soft and easily scratched. Handle this polarizer carefully.
- 11.1.4 If the display surface is contaminated, blow on the surface and gently wipe it with a soft dry cloth. If it is still not completely clear, moisten the cloth with ethyl alcohol.
- 11.1.5 Solvents may damage the polarizer. Do not use water, ketone or aromatic solvents except ethyl alcohol.
Do not attempt to disassemble the AMOLED Module.
- 11.1.6 If the logic circuit power is off, do not apply the input signals.
- 11.1.7 To prevent destruction from static electricity, be careful to maintain an optimum working environment.
- 11.1.8 Be sure to make yourself in contact with the ground when handling with the AMOLED Modules.
- 11.1.9 Tools required for assembly, such as soldering irons, must be properly ground.
- 11.1.10 To reduce the generation of static electricity, do not conduct assembly or other work under dry conditions.
- 11.1.11 To protect the display surface, the AMOLED Module is coated with a film. Be careful when peeling off this protective film, because static electricity may generate.

11.2 Storage Precautions:

- 11.2.1 When storing the AMOLED modules, be sure that they are not directly exposed to the sunlight or the light of fluorescent lamps.
- 11.2.2 The AMOLED modules should be stored under the storage temperature range. If the AMOLED modules will be stored for a long time, the recommended condition is:
Temperature: 0°C ~ 40°C Relatively humidity: ≤ 80 %
- 11.2.3 The AMOLED modules should be stored in the room without acid, alkali or harmful gas.

11.3 Transportation Precautions:

- 11.3.1 The AMOLED modules should not be suffered from falling and violent shocking during transportation. Besides, excessive pressure, water, damp and sunshine, should be avoided.